

# Daisy Chain Protocol Development in Force-Guiding Particle Chains for Shape-Shifting Displays Development Board Implementation

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## What this session covers

- physical network structure
- MCU selection
- development board

## Underlying work

### Force-Guiding particle Chains for Shape-Shifting Displays[1]

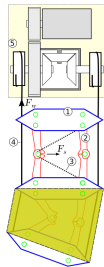


Figure 1:  
particle chain

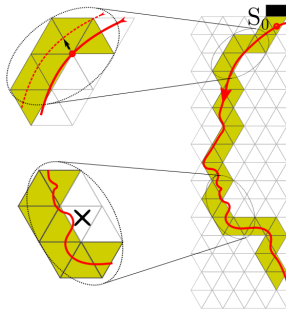


Figure 2: folding a shape

chain is stretched in natural state  
 shape Memory Alloy used as actuator (3)  
 joints unlocked by actuators (2)  
 force  $F_s$  folds chain

## Approach & limitation

current particle implements 1-Wire via power supply wires  
energy must be buffered before communication starts  
power must be switched off/on  
automatic chain position detection is costly

## Idea

decouple communication from power supply (4)  
using a daisy-chain protocol, and  
actuator wires (3)

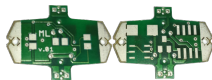


Figure 3: *particle PCB*

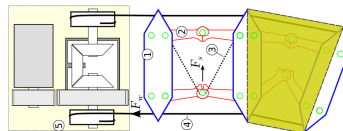


Figure 4: *particle chain*

## Project extent

particle board development  
easy accessible test points and transmission wires  
flexible and fast network assembly

## Project constraints

reasonable low level MCU  
minimize number of components on particle PCB  
communication:

- exploit SMA wires
- decouple from power supply

small MCU package in final productive particle  
single communication entry point to the network

## Network approach - I

exploit actuator wires  
also for communication

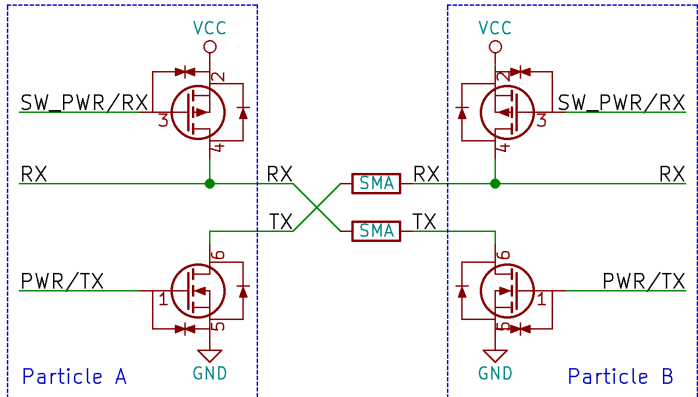


Figure 5: *transmission and reception wiring*

## Network approach - II

linear network

daisy chained participants

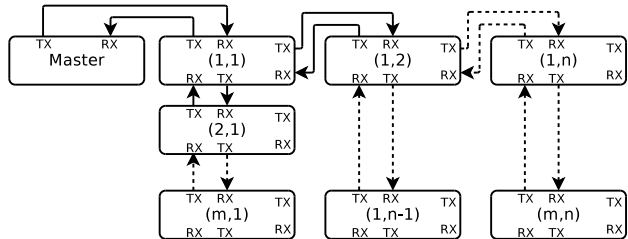
### Advantages

- + simple to implement
- + no media access control
- + no loops
- + no dynamic routes

### Disadvantages

- error detaches segment
- no recovery for segment

**Figure 6:**  
*network topology*



## MCU requirements - capabilities

three separate external interrupts

self programmable EEPROM

for firmware replication (future work)

package size

small package for productive particle

bigger package for development board



## MCU memory requirements - upper bound estimation

### Flash

expected max. firmware size:  $\sim 4k$  SLOC  
 estimated object code bytes per SLOC [2]  $\sim 4.0B$   
 flash usage estimation:  
 $4k * 4B =$   $\sim 16kB$

### SRAM

tx/rx buffers: 3 ports, 8byte  
 $3 * 8B * 2 =$  16B  
 Manchester code decoding buffer  
 with 2 flank time stamps per bit  
 $3 * 8 * 2 * \text{sizeof}(\text{uint16\_t})B * 0.75 =$  576B  
 other global variables 200B  
 stack: max. 50 nested void function  
 calls with  $\sim (1 * \text{uint8\_t})$  argument  
 $50 * (1 + 2)B =$  150B  
 SRAM estimation:  $\sim 950B$

## Candidates

candidates are all ATTiny20 family MCUs having  
 $\geq 16kB$  flash and  
 $\geq 1kB$  SRAM

## Comparison of used MCUs

	<b>ATTiny20 (proof of concept)</b>	<b>ATTiny1634</b>
# pin change int.	sufficient	sufficient
EEPROM	no	yes
flash	2kB	16kB
SRAM	128B	1kB
small package	3mm × 3mm	4mm × 4mm
alternative pkg.	no	yes, SOIC

## The prototype

- not satisfying new requirements
- too small/unhandy for development

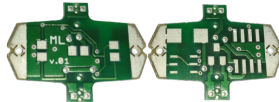


Figure 7: *prototype*

## Version 1.0

- linear chain of development particles  
+ not mounted in chain mechanics  
- but still time consuming assembly

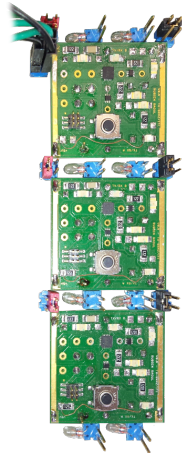


Figure 8: *Version 1.0*

## Version 1.1

### Advantages

- + repetitive design
- + configurable network shape

### Disadvantages

- costly soldering
- expensive connectors
- one faulty particle breaks whole PCB

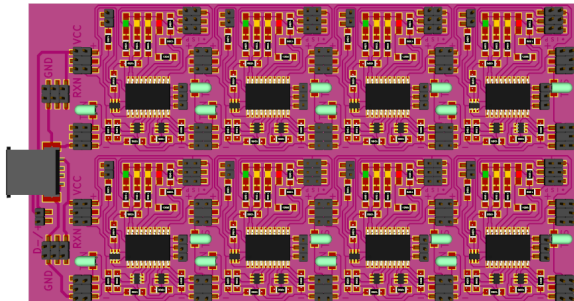


Figure 9: Version 1.1 - particle array PCB

## Version 1.21

configurable network dimension  
easy extensible network  
faulty particles can be replaced  
cheaper  
higher particle density

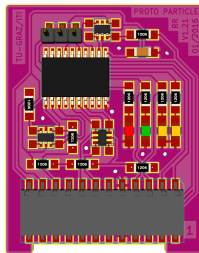


Figure 10: *pluggable particle*

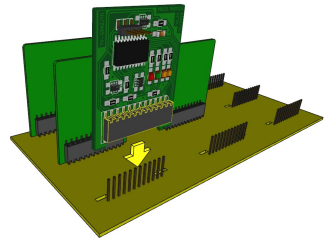


Figure 11: *grid board*

# Results

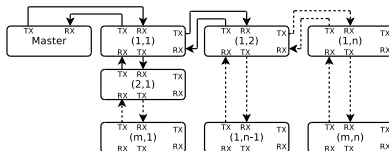


Figure 12: *network structure*

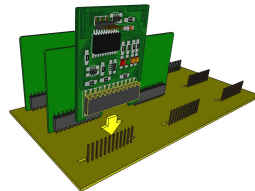
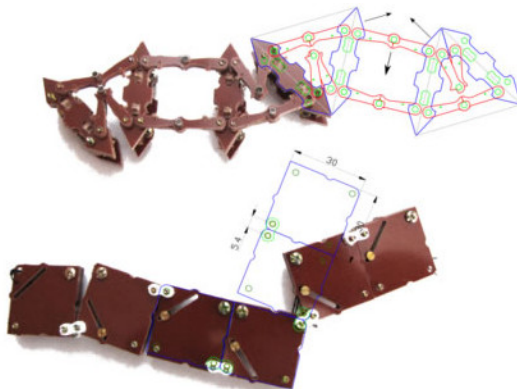


Figure 13: *pluggable particle module*



## Future work

### hardware

- simplify development board

- enhance grid board

### communication protocol

- Physical Layer: implement coding

- Data Layer: fault detection

- Network Layer: self enumeration, addressing,  
synchronization, clock compensation  
task scheduling (TDM of communication and tasks)

- runtime compensation of RC-oscillator discrepancy

- firmware replication: customize boot loader





M. Lasagni and K. Römer, “Force-guiding particle chains for shape-shifting displays,” *CoRR*, vol. abs/1402.2507, 2014.



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